Pressure-Sensor Assembly Technique

An essential underfilling step can be performed without compromising a diaphragm.

Nielsen Engineering & Research (NEAR) recently developed an ultrathin data acquisition system for use in turbomachinery testing at NASA Glenn Research Center. This system integrates a microelectromechanical-systems (MEMS)-based absolute pressure sensor [0 to 50 psia (0 to 345 kPa)], temperature sensor, signal-conditioning application-specific integrated circuit (ASIC), microprocessor, and digital memory into a package which is roughly 2.8 in. (7.1 cm) long by 0.75 in. (1.9 cm) wide. Each of these components is flip-chip attached to a thin, flexible circuit board and subsequently ground and polished to achieve a total system thickness of 0.006 in. (0.15 mm). Because this instrument is so thin, it can be quickly adhered to any surface of interest where data can be collected without disrupting the flow being investigated.

One issue in the development of the ultrathin data acquisition system was how to attach the MEMS pressure sensor to the circuit board in a manner which allowed the sensor's diaphragm to communicate with the ambient fluid while providing enough support for the chip to survive the grinding and polishing operations. The technique, developed by NEAR and Jabil Technology Services Group (San Jose, CA), is described below. In the approach developed, the sensor is attached to the specially designed circuit board, see Figure 1, using a modified flip-chip technique. The circular diaphragm on the left side of the sensor is used to actively measure the ambient pressure, while the diaphragm on the right is used to compensate for changes in output due to temperature variations. The circuit board is fabricated with an access hole through it so that when the completed system is installed underfilled to support the chip during the soldering, but before underfilling, is provided. The technique described provides a means for securely attaching and underfilling a MEMS-based pressure sensor to a circuit board while allowing the diaphragm access to the ambient fluid.

This work was done by Daniel A. Pruzan of Nielsen Engineering and Research for Glenn Research Center. Refer to LEW-17212.

Wafer-Level Membrane-Transfer Process for Fabricating MEMS

This process is well suited for structures fabricated on dissimilar substrates.

A process for transferring an entire wafer-level micromachined silicon structure for mating with and bonding to another such structure has been devised. This process is intended especially for use in wafer-level integration of microelectromechanical systems (MEMS) that have been fabricated on dissimilar substrates.

Unlike in some older membrane-transfer processes, there is no use of wax or epoxy during transfer. In this process, the substrate of a wafer-level structure to be transferred serves as a carrier, and is etched away once the transfer has been completed. Another important feature of this process is that two...
wafer-level structures to be integrated with each other are indium-bump-bonded together; this is advantageous in that it produces less stress during bonding of structures formed on two dissimilar wafers. Moreover, unlike in some older membrane-transfer processes, there is no incidental release of HF from the final structure — an advantage when indium, aluminum, or another soft metal is used for bonding.

This process was demonstrated by applying it to the joining of (1) a corrugated polycrystalline silicon (polysilicon) membrane that had been fabricated by patterning and etching on a silicon-on-insulator (SOI) wafer with (2) a silicon substrate. A 1-µm thick corrugated polysilicon membrane has been transferred onto an electrode wafer to show the feasibility of the proposed technique. The transferred membrane with underlying

Figure 1. An Outline of the Process shows the key steps.

Figure 2. A Corrugated Polysilicon Membrane, only 1 µm thick, was transferred onto a silicon substrate to form an array of electrostatic actuators. The actuators were found to function as intended.
A Reactive-Ion Etch for Patterning Piezoelectric Thin Film

Gaseous mixtures BCl₃ and Cl₂ are highly selective for etching PbZr₁₋ₓTiₓO₃ films.

Reactive-ion etching (RIE) under conditions described below has been found to be a suitable means for patterning piezoelectric thin films made from such materials as PbZr₁₋ₓTiₓO₃ or Ba₃SrₓTiO₃. In the original application for which this particular RIE process was developed, PbZr₁₋ₓTiₓO₃ films 0.5 µm thick are to be sandwiched between Pt electrode layers 0.1 µm thick and Ir electrode layers 0.1 µm thick to form piezoelectric capacitor structures. Such structures are typical of piezoelectric actuators in advanced microelectromechanical systems now under development or planned to be developed in the near future.

RIE of PbZr₁₋ₓTiₓO₃ is usually considered to involve two major subprocesses: an ion-assisted-etching reaction, and a sputtering subprocess that removes reactive byproducts. RIE is favored over other etching techniques because it offers a potential for a high degree of anisotropy, high-resolution pattern definition, and good process control. However, conventional RIE is not ideal for patterning PbZr₁₋ₓTiₓO₃ films at a thickness as great as that in the original intended application. In order to realize the potential benefits mentioned above, it is necessary to optimize process conditions — in particular, the composition of the etching gas and the values of such other process parameters as radio-frequency power, gas pressure, gas-flow rate, and duration of the process. Guidelines for determining optimum conditions can be obtained from experimental determination of etch rates as functions of these parameters.

Etch-gas mixtures of BCl₃ and Cl₂, some also including Ar, have been found to offer a high degree of selectivity as needed for patterning of PbZr₁₋ₓTiₓO₃ films on top of Ir electrode layers in thin-film capacitor structures. The selectivity is characterized by a ratio of ≈10:1 (rate of etching PbZr₁₋ₓTiₓO₃ ÷ rate of etching Ir and IrOₓ). At the time of reporting the information for this article, several experiments on RIE in BCl₃ and Cl₂ (and sometimes Ar) had demonstrated the 10:1 selectivity ratio, and further experiments to enhance understanding and obtain further guidance for optimizing process conditions were planned.

This work was done by Eui-Hyeok Yang and Larry Wild of Caltech for NASA’s Jet Propulsion Laboratory. For further information, access the Technical Support Package (TSP) free on-line at www.nasatech.com.

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